



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE42764E V50		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000970668						
<b>Package</b>		PG-SSOP-14-2		<b>Weight*</b>		83.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.179	3.81	3.81	38077	38077
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8253	
wire	non noble metal	copper	7440-50-8	27.978	33.51	34.39	335114	343883
	noble metal	gold	7440-57-5	0.109	0.13	0.13	1305	1305
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.12		1155
plastics	plastics	epoxy resin	-	4.434	5.31		53108	
	inorganic material	silicondioxide	60676-86-0	43.664	52.30	57.73	523003	577266
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11692	11692
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9194	9194
glue	plastics	epoxy resin	-	0.388	0.46		4646	
	noble metal	silver	7440-22-4	1.164	1.39	1.85	13937	18583
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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